



BYD Microelectronics Co., Ltd.

BF9028DND-A

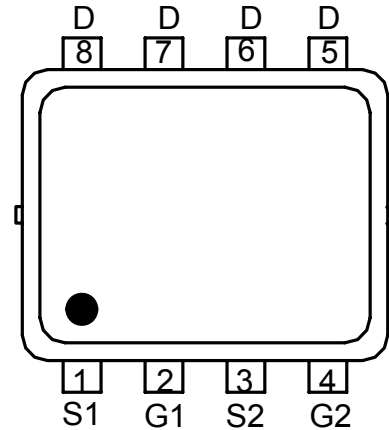
20V N-Channel MOSFET

General Description

The BF9028DND-A is a Dual N-Channel MOS Field Effect Transistor, which is applied to electronic systems as a power switch. This device has ESD-protection and low resistance characteristics.

Features

- $V_{DS} = 20V$
- $I_D = 6A$
- Low on-state resistance
- $R_{DS(on)} = 16.0m\Omega$ TYP($V_{GS} = 4.5V$, $I_D = 3.0A$)
- $R_{DS(on)} = 17.5m\Omega$ TYP($V_{GS} = 3.8V$, $I_D = 3.0A$)
- $R_{DS(on)} = 20.0m\Omega$ TYP($V_{GS} = 3.0V$, $I_D = 3.0A$)
- $R_{DS(on)} = 23.0m\Omega$ TYP($V_{GS} = 2.5V$, $I_D = 3.0A$)
- Built-in G-S protection diode against ESD
- Lead Pb-free and Halogen-free



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Drain to Source Voltage	V_{DS}	20	V
Gate to Source Voltage	V_{GS}	± 10	V
Drain Current (DC)	$I_{D(DC)}$	6	A
Drain Current (pulse) ^a	$I_{D(pulse)}$	24	A
Maximum Power Dissipation ^b	P_D	2.0	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{stg}	-55~+150	°C

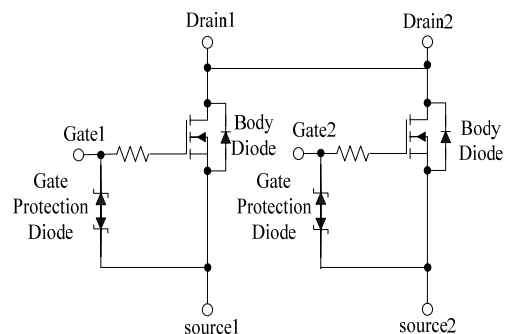
Notes a. $PW < 10\mu s$, Duty Cycle $< 1\%$, $V_{GS} = 4.5V$.

b. Mounted on ceramic substrate of $45\text{ cm}^2 \times 2.2\text{mm}$.

Caution: These values must not be exceeded under any conditions.

Remark: The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

EQUIVALENT CIRCUIT



Ordering Information

Part Number	BF9028DND-A
Package	DFN3*3-8L

Electrical Characteristics ($T_A = 25^\circ\text{C}$)

Characteristic	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$	—	—	10	μA
Gate Leakage Current	I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$	—	—	± 10	μA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 0.25mA$	0.5	0.8	1.5	V
Forward Transfer Admittance	$ y_{fs} $	$V_{DS} = 10V, I_D = 3A$	—	4	—	S
Drain to Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 3A$	—	16	22	$m\Omega$
		$V_{GS} = 3.8V, I_D = 3A$	—	17.5	24	$m\Omega$
		$V_{GS} = 3.0V, I_D = 3A$	—	20	26	$m\Omega$
		$V_{GS} = 2.5V, I_D = 3A$	—	23	30	$m\Omega$
Input Capacitance	C_{iss}	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$	—	1200	—	pF
Output Capacitance	C_{oss}		—	260	—	pF
Reverse Transfer Capacitance	C_{rss}		—	250	—	pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 10V, I_D = 3A, V_{GS} = 4.5V, R_G = 10\Omega$	—	160	—	ns
Rise Time	t_r		—	500	—	ns
Turn-off Delay Time	$t_{d(off)}$		—	2600	—	ns
Fall Time	t_f		—	1600	—	ns
Total Gate Charge	Q_G	$V_{DS} = 16V, V_{GS} = 4.5V, I_D = 6A$	—	10	—	nC
Gate to Source Charge	Q_{GS}		—	2.5	—	nC
Gate to Drain Charge	Q_{GD}		—	3.5	—	nC
Body Diode Forward Voltage	$V_{F(S-D)}$	$I_F = 6A, V_{GS} = 0V$	—	0.7	1.2	V

Typical characteristics (25°C unless noted)

Figure 1 Threshold Voltage vs. Temperature

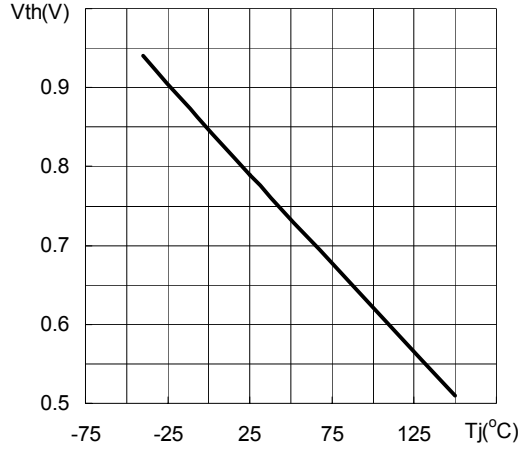


Figure 2 BV_{DSS} vs. Temperature

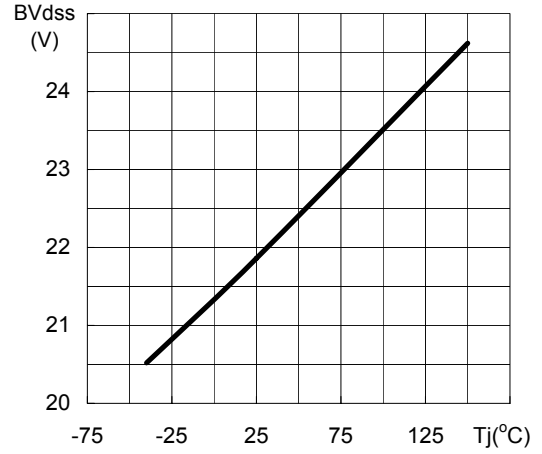


Figure 3 I_{DSS} vs. Temperature

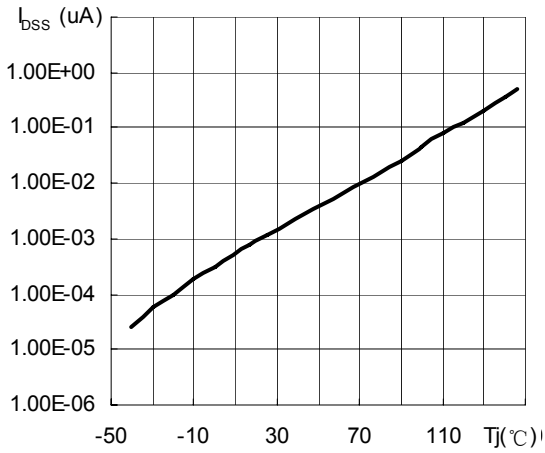


Figure 4 I_{GSS} vs. Temperature

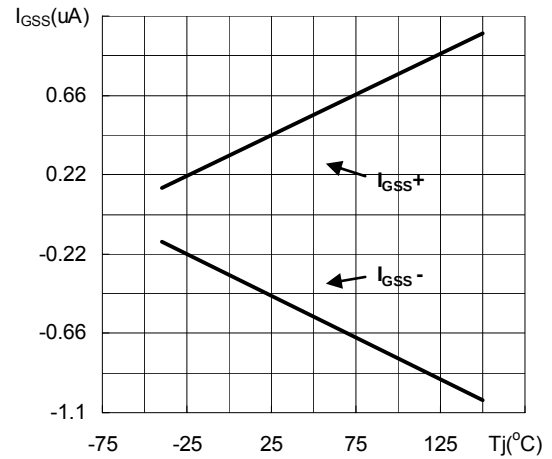


Figure 5 On-Resistance vs. Temperature

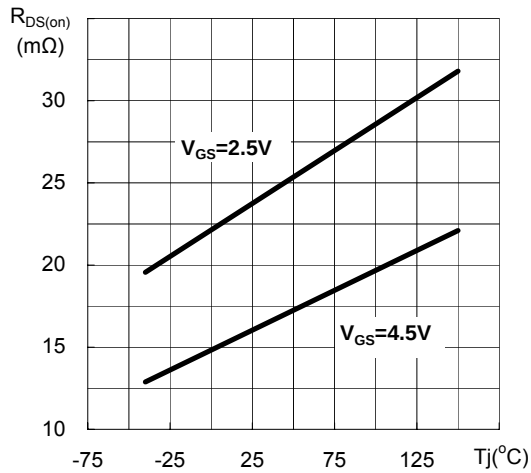
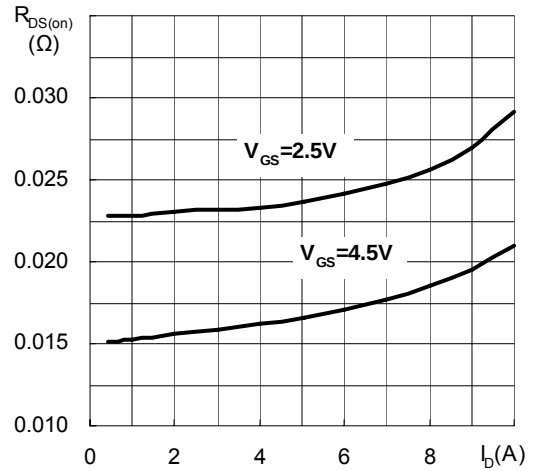
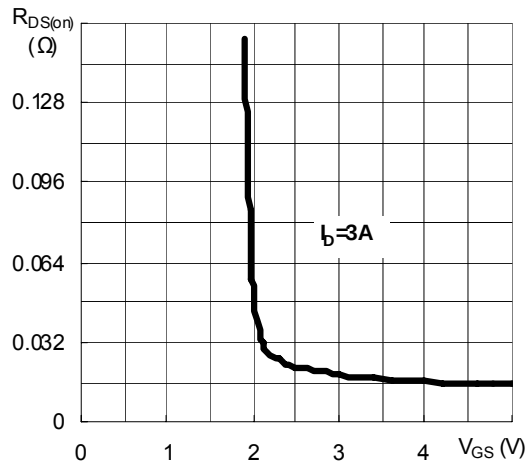


Figure 6 On-Resistance vs. Drain Current



**Figure 7 On-Resistance
vs. Gate-to-Source Voltage**



**Figure 8 Drain to Source Voltage
vs. Drain Current**

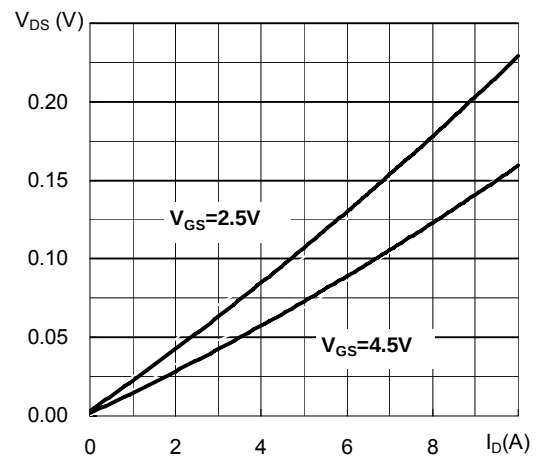
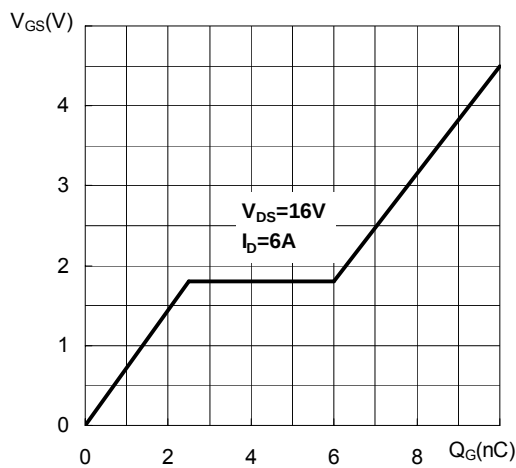
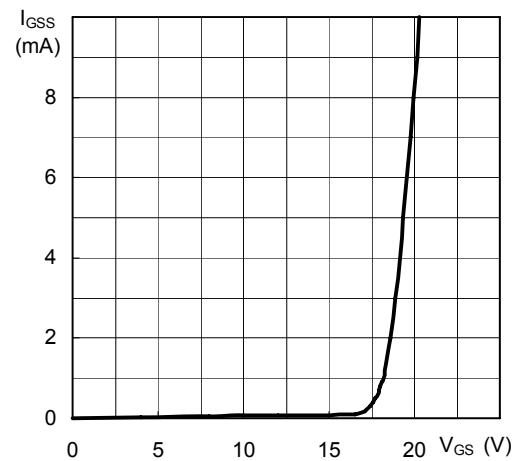


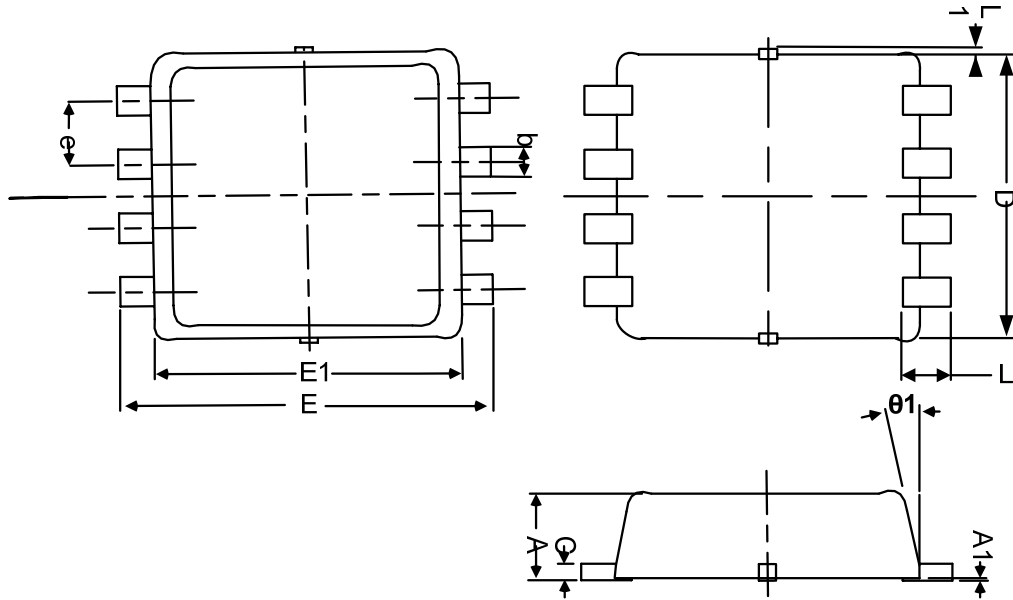
Figure 9 Gate Charge



**Figure 10 Gate-Current
vs. Gate-Source Voltage**



Package Drawing



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.70	0.80	0.90	0.0276	0.0315	0.0354
A1	0.00	0.00	0.05	0.000	0.000	0.002
b	0.24	0.30	0.35	0.009	0.012	0.014
C	0.08	0.152	0.25	0.003	0.006	0.010
D	2.80	2.90	3.00	0.110	0.114	0.118
E	2.70	2.80	2.90	0.106	0.110	0.114
E1	2.20	2.30	2.40	0.087	0.091	0.094
e	0.65BSC			0.026BSC		
L	0.2	0.375	0.450	0.008	0.0148	0.0177
L1	0.000	0.000	0.100	0.000	0.000	0.004
θ	0°	10°	12°	0°	10°	12°



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